

F/G. 1 PRIOR ART

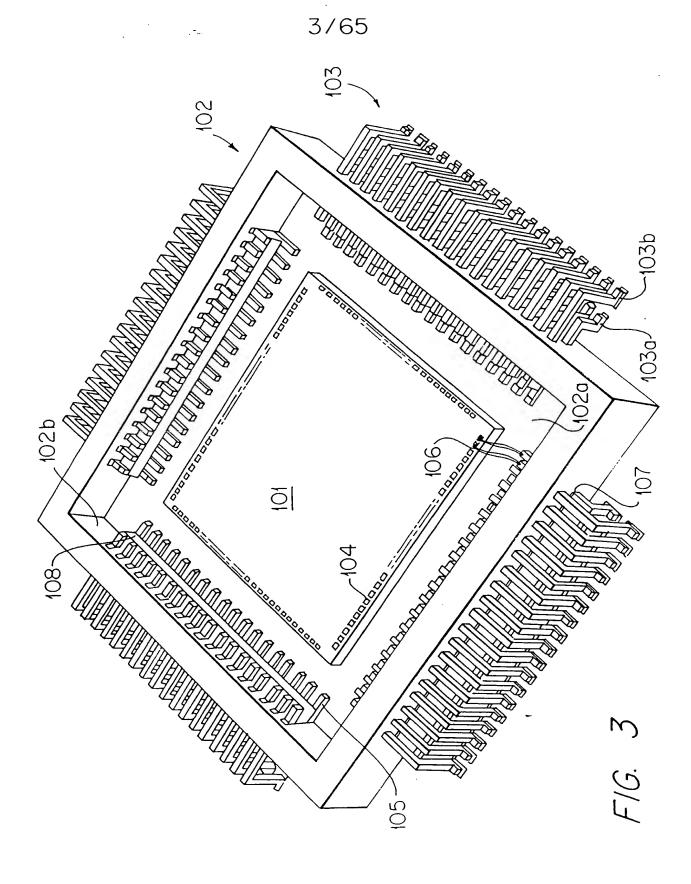
THROUGH HOLE PACKAGE

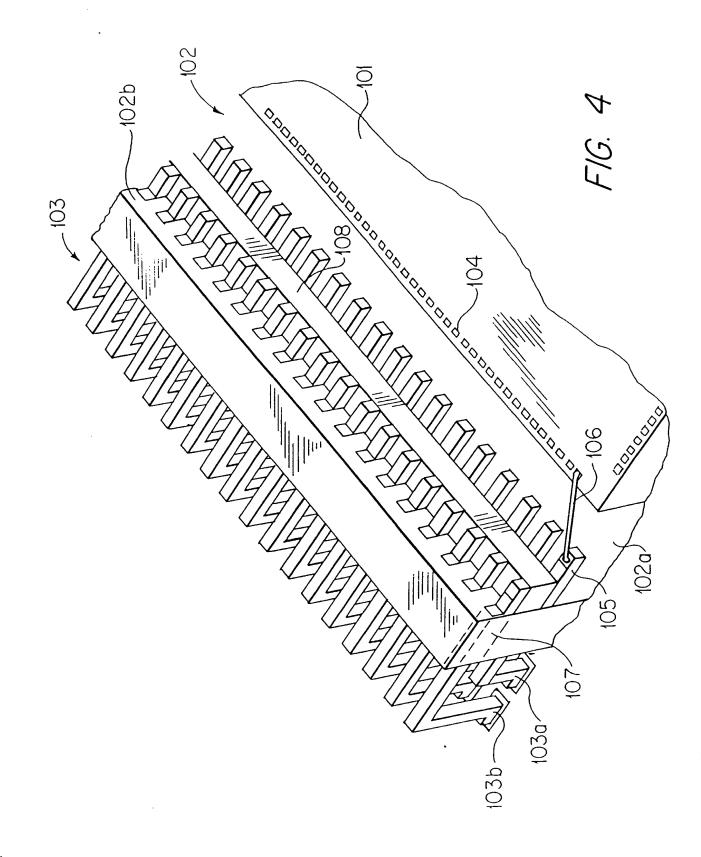
DIP (DUAL IN-LINE PACKAGE) SH-DIP (SHRINK DIP) SK-DIP DL-DIP (SKINNY DIP, SLIM DIP) SIP (SINGLE **ÎN-LINE** PACKAGE) ZIP (ZIG-ZAG **IN-LINE** PACKAGE) PGA (PIN GRID ÀRRAY)

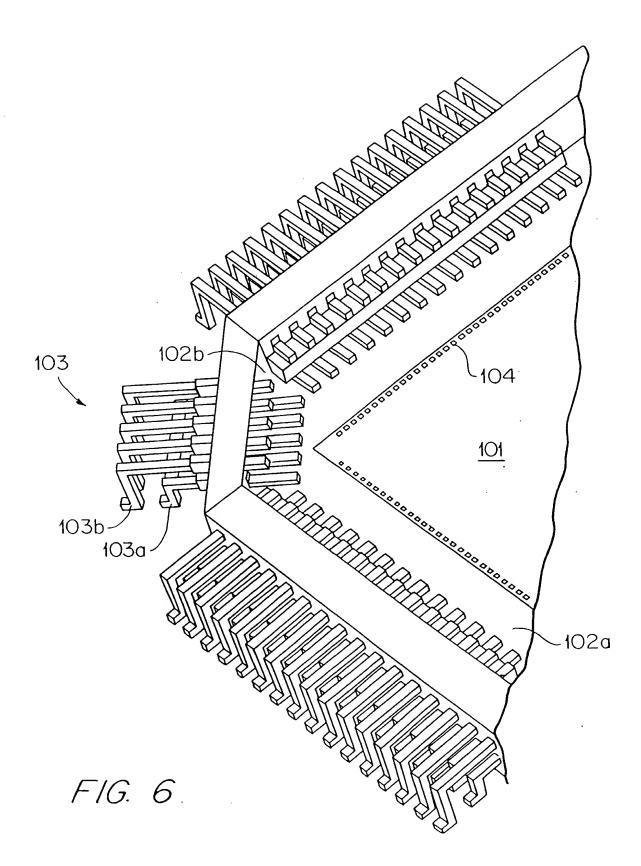
SURFACE MOUNTED PACKAGE

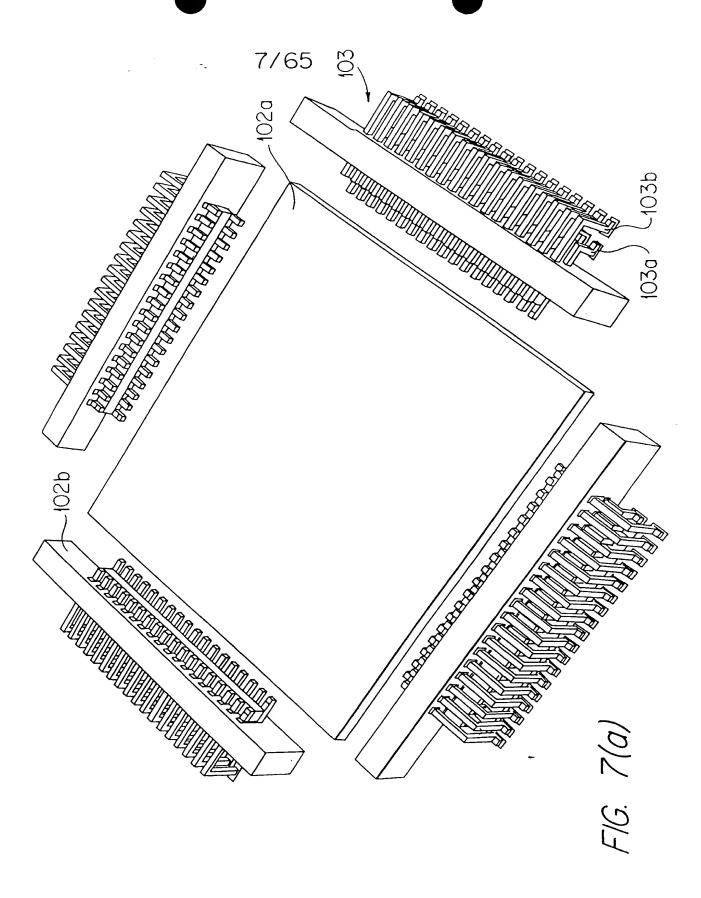
TOTAL TOTAL	SO OR SOP (SMALL OUT- LINE PACKAGE)
STATE OF THE PARTY	QFP (QUAD FLAT PACKAGE)
	LCC (LEADLESS CHIP CARRIER)
	PLCC SOJ (PLASTIC LEADED CHIP CARRIER WITH BUTT LEADS)

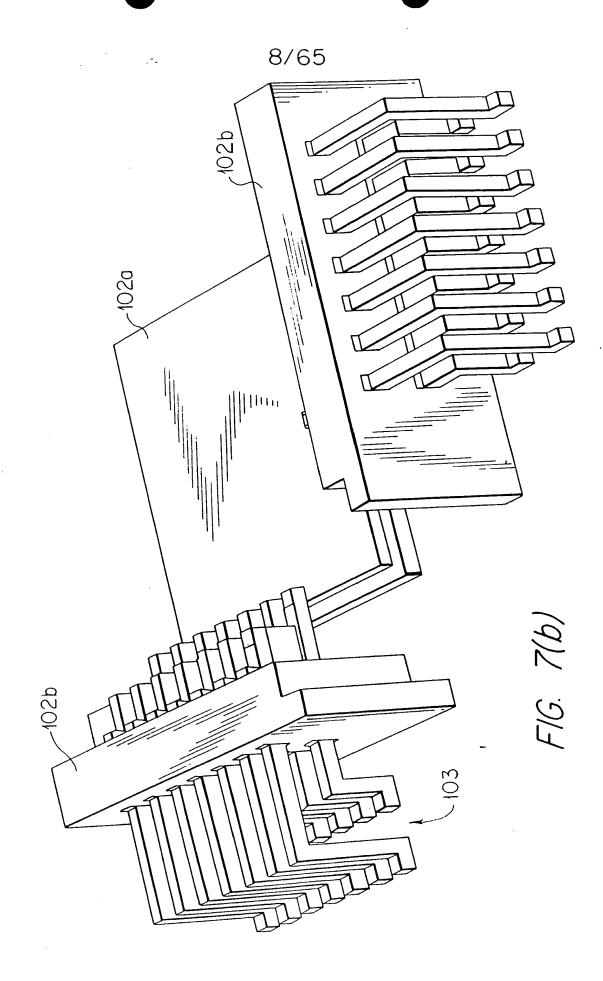
FIG. 2

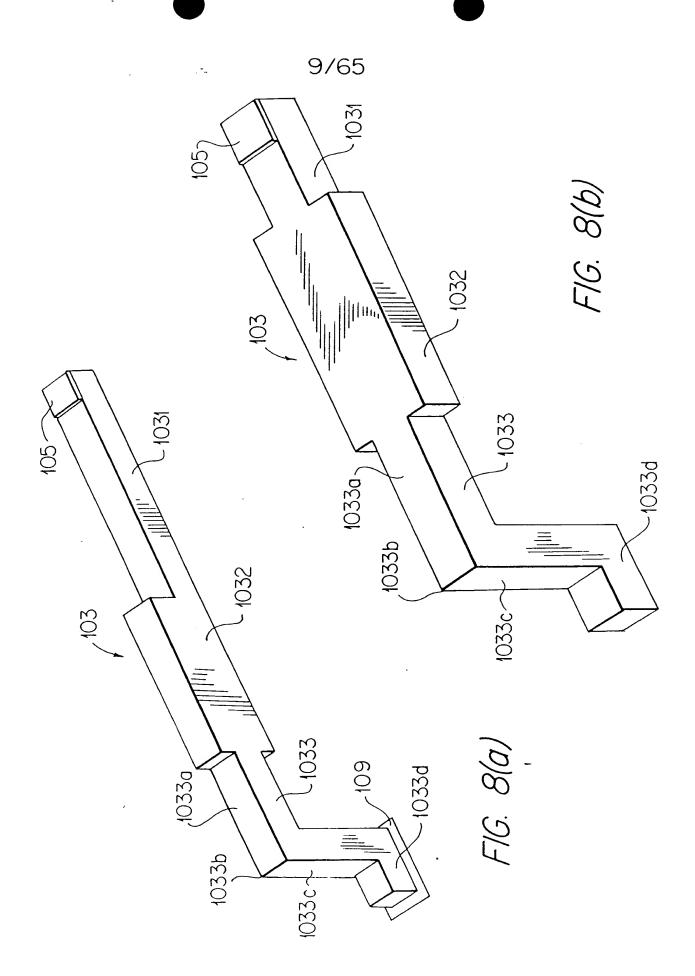


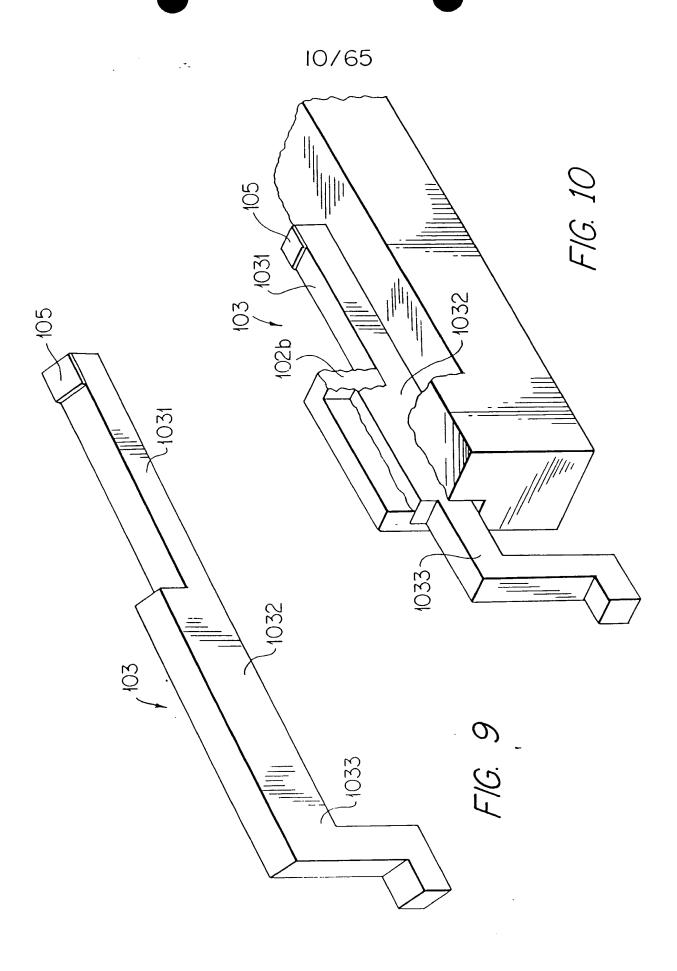


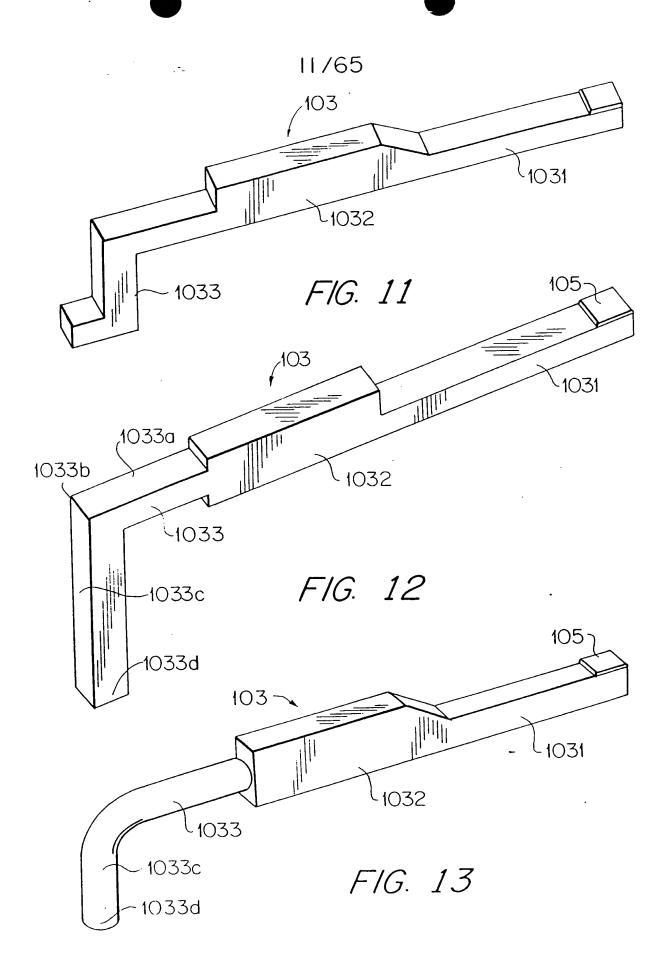


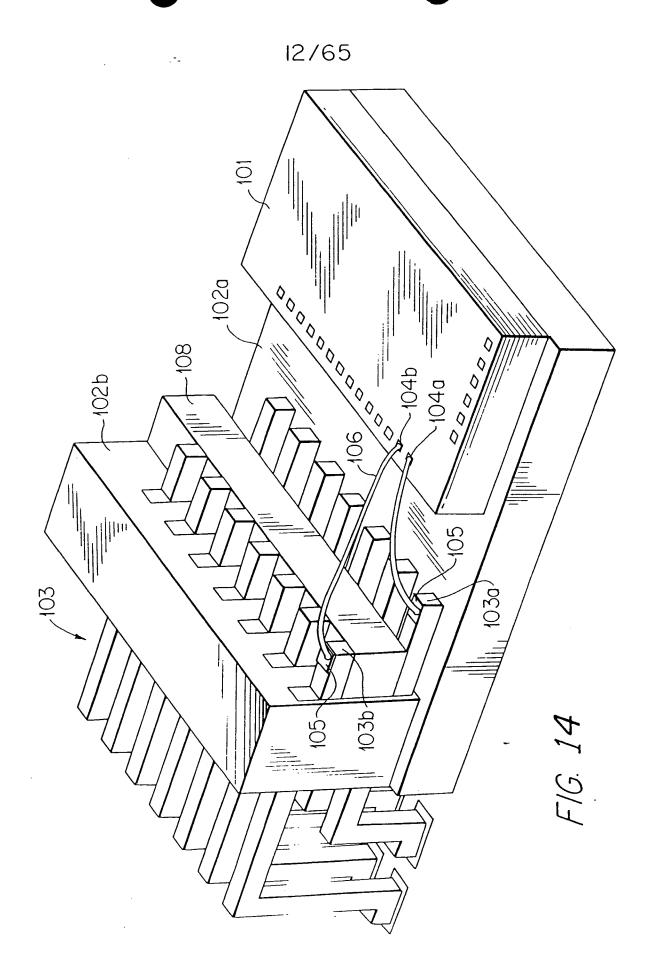


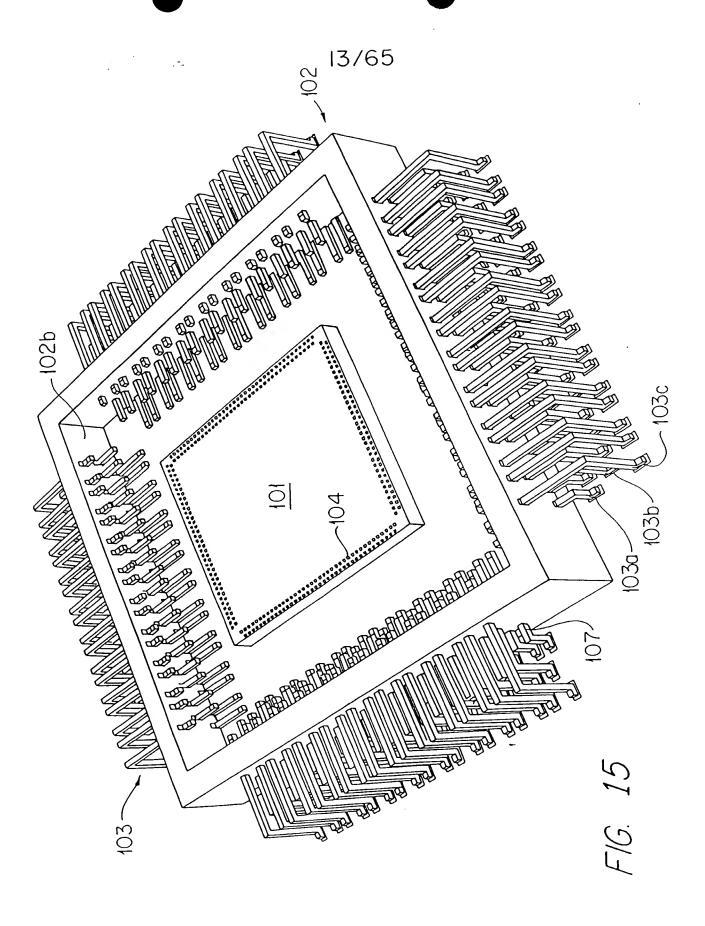




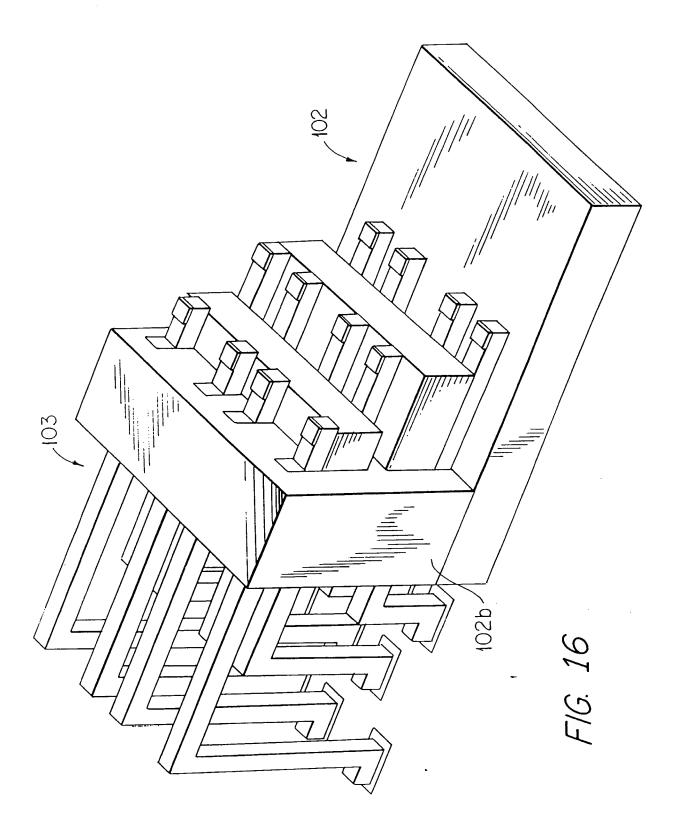


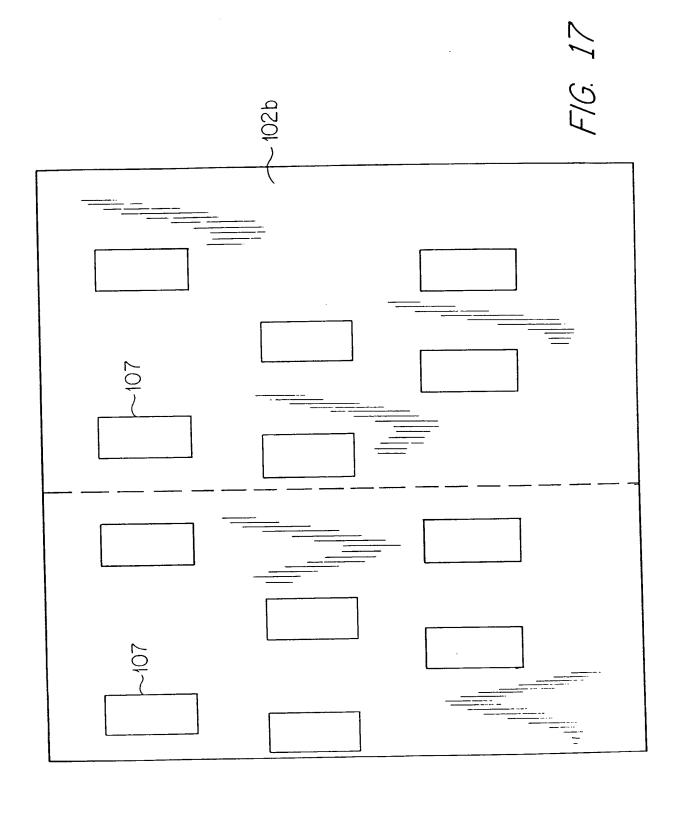




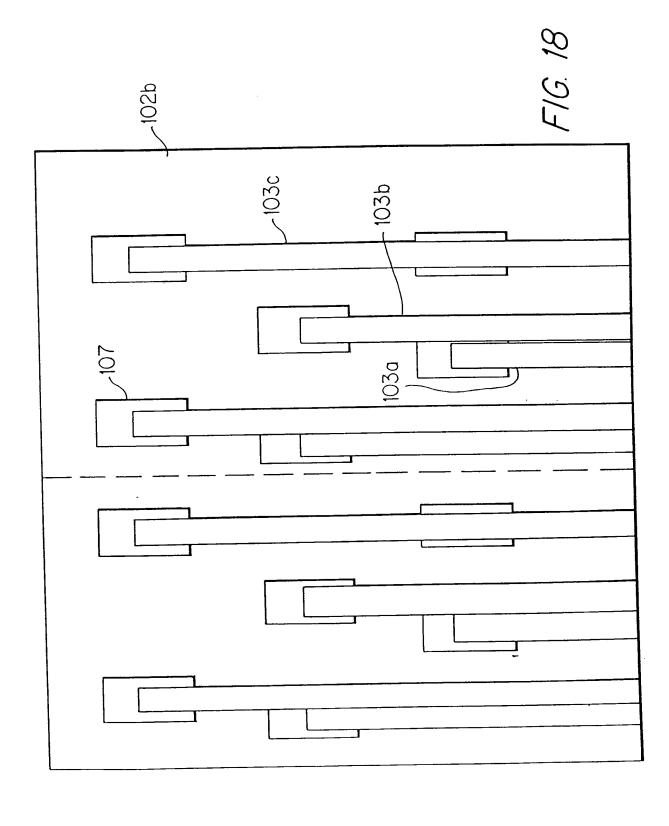


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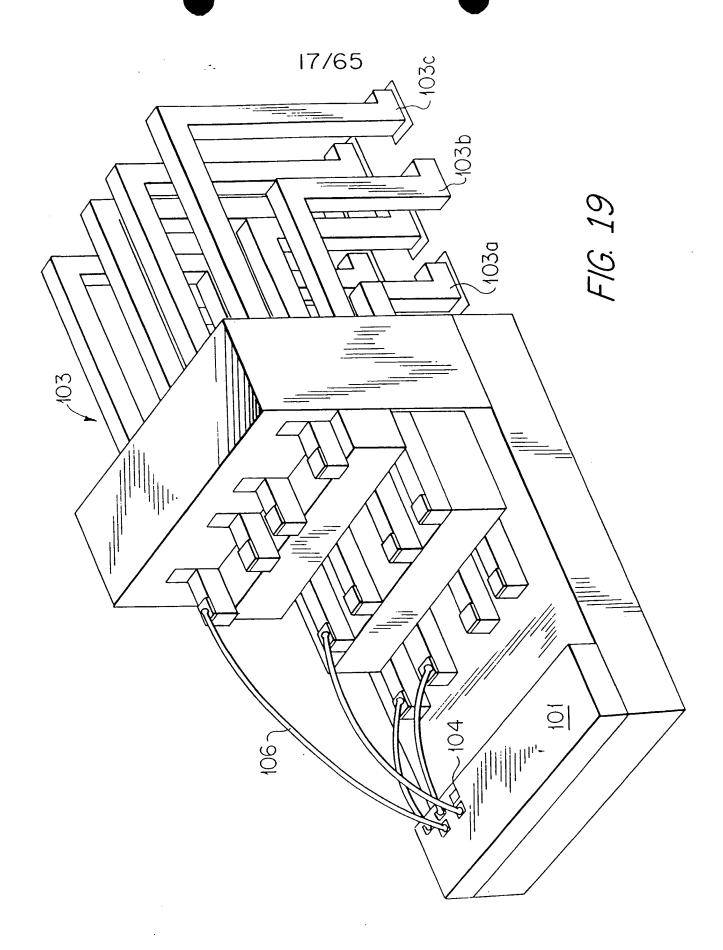


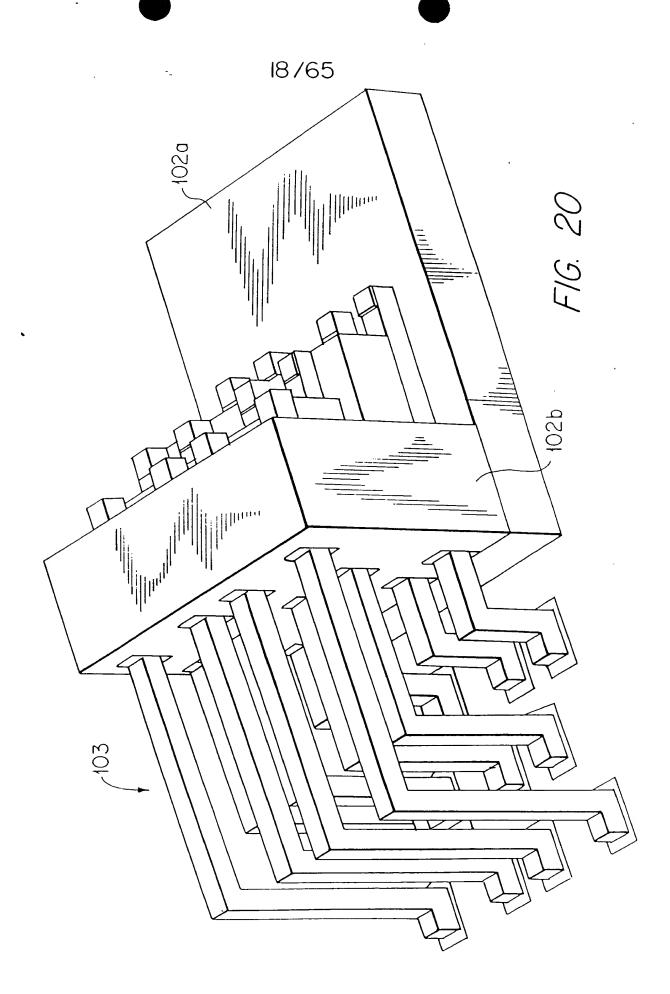


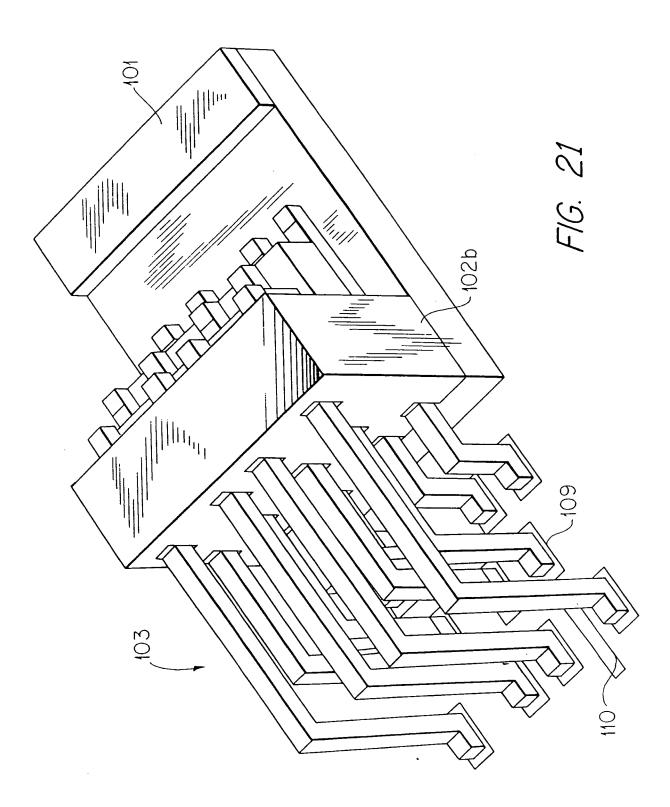
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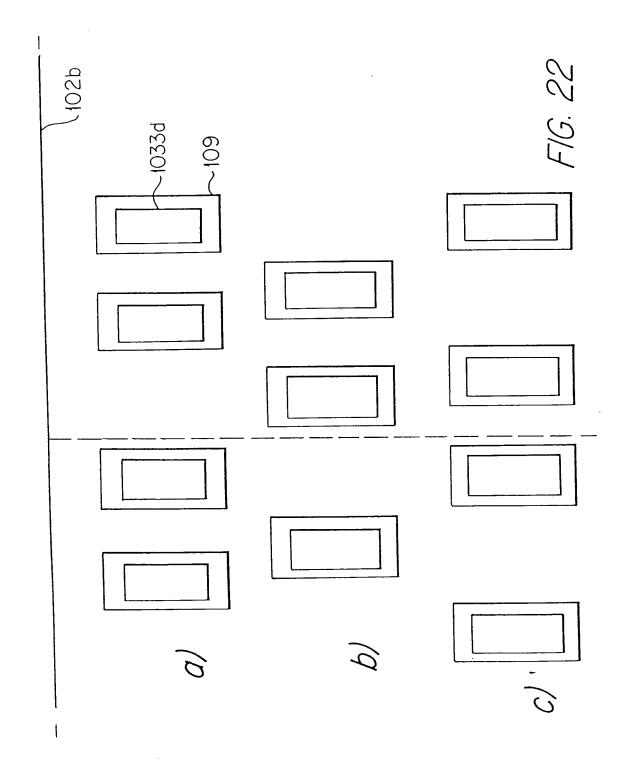


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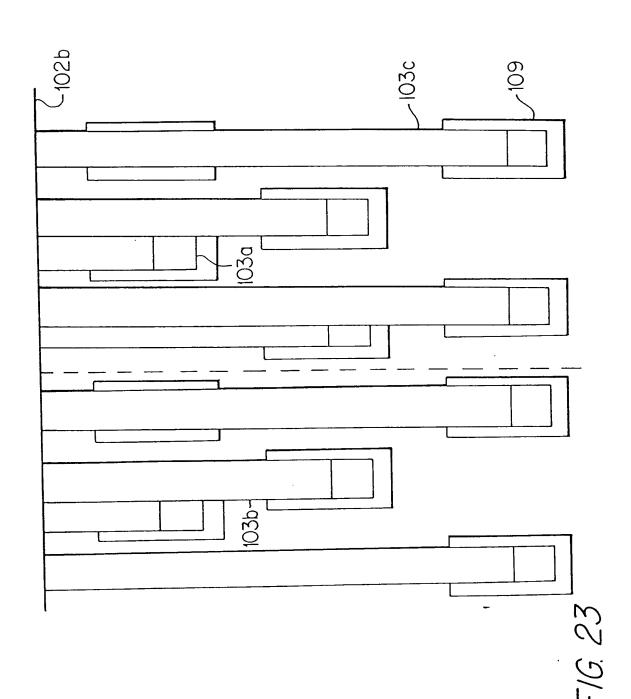


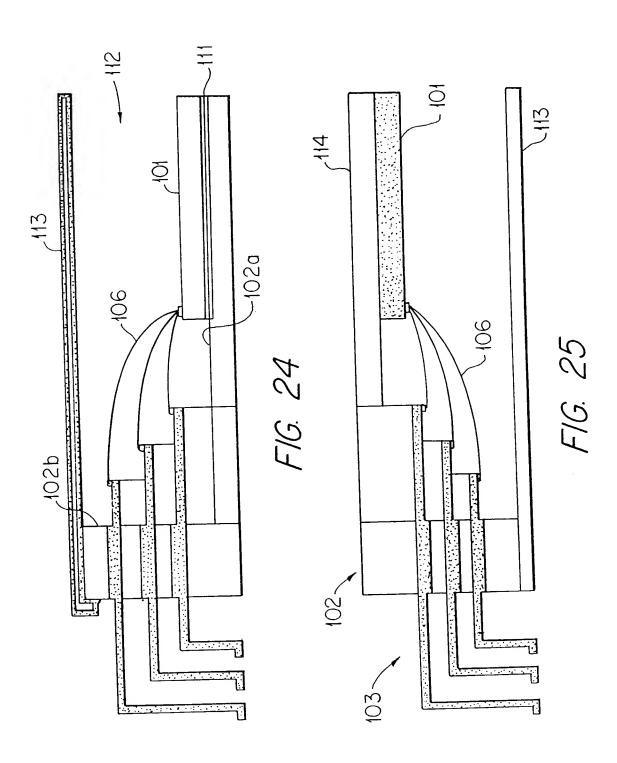












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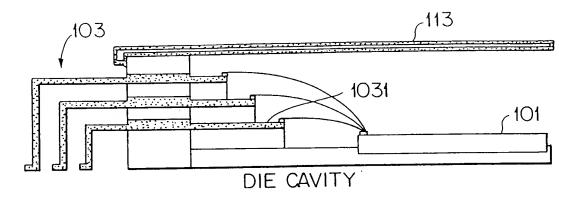


FIG. 26

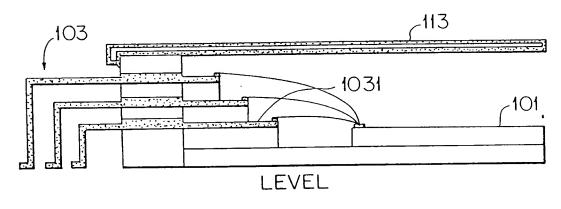


FIG. 27

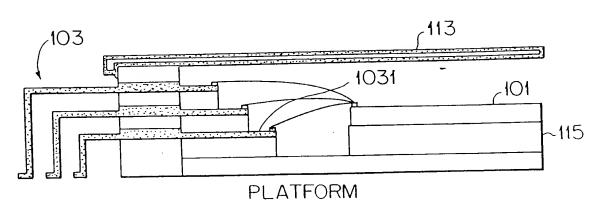
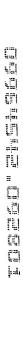
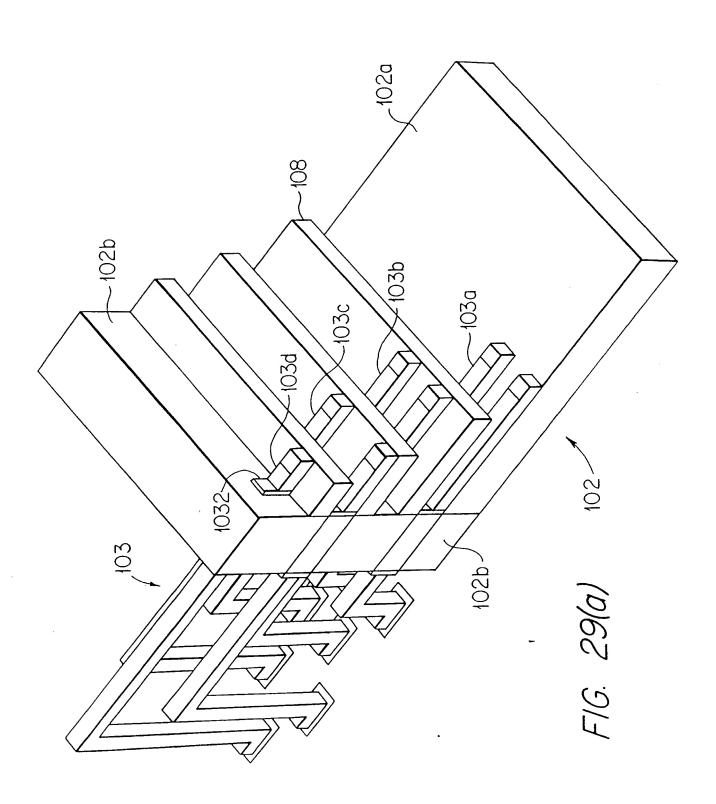
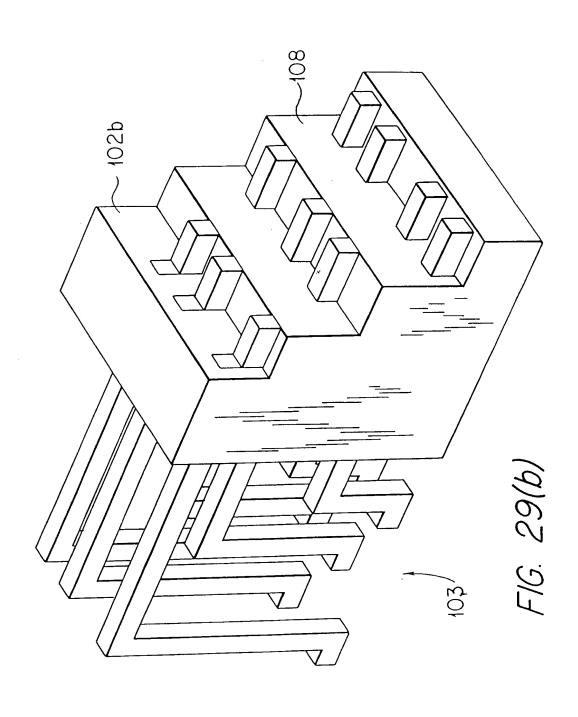
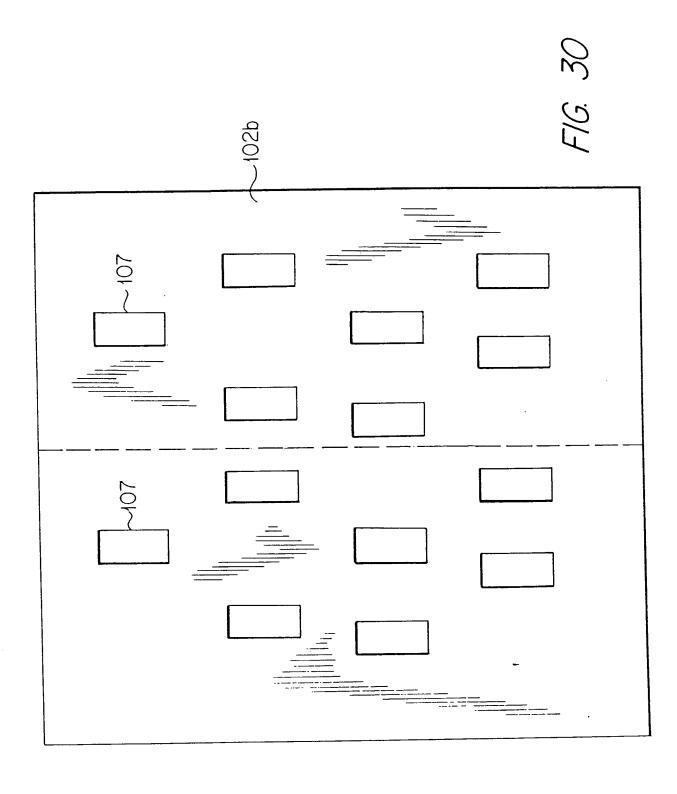


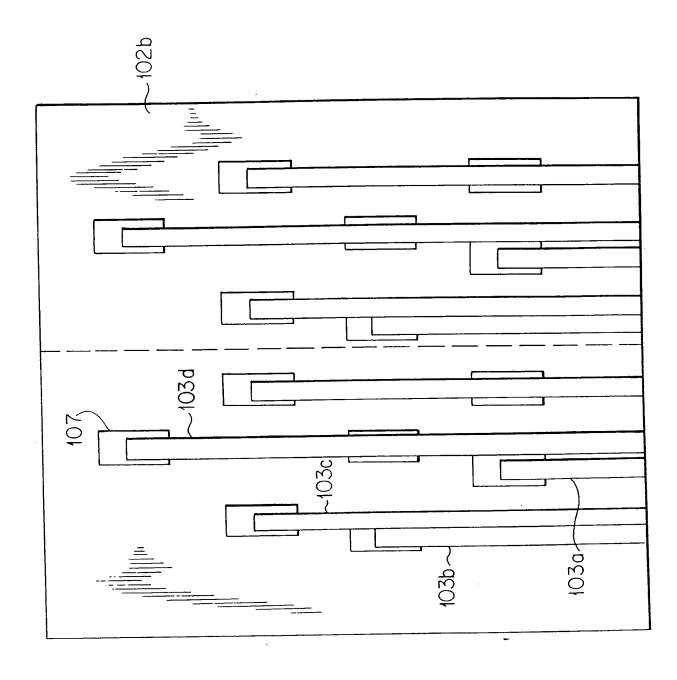
FIG. 28



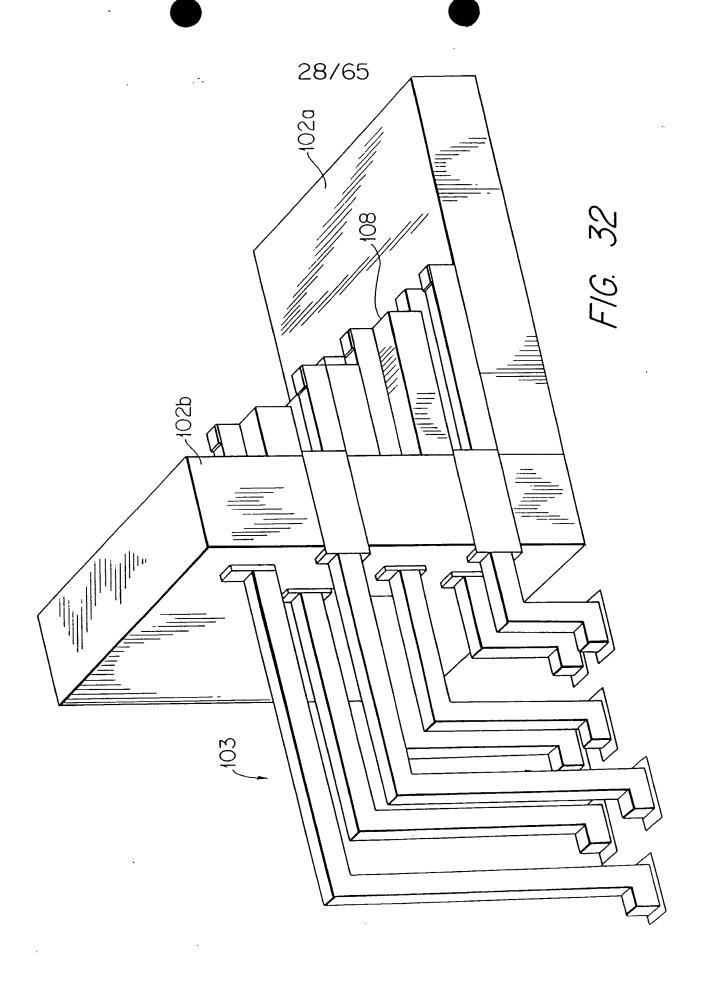


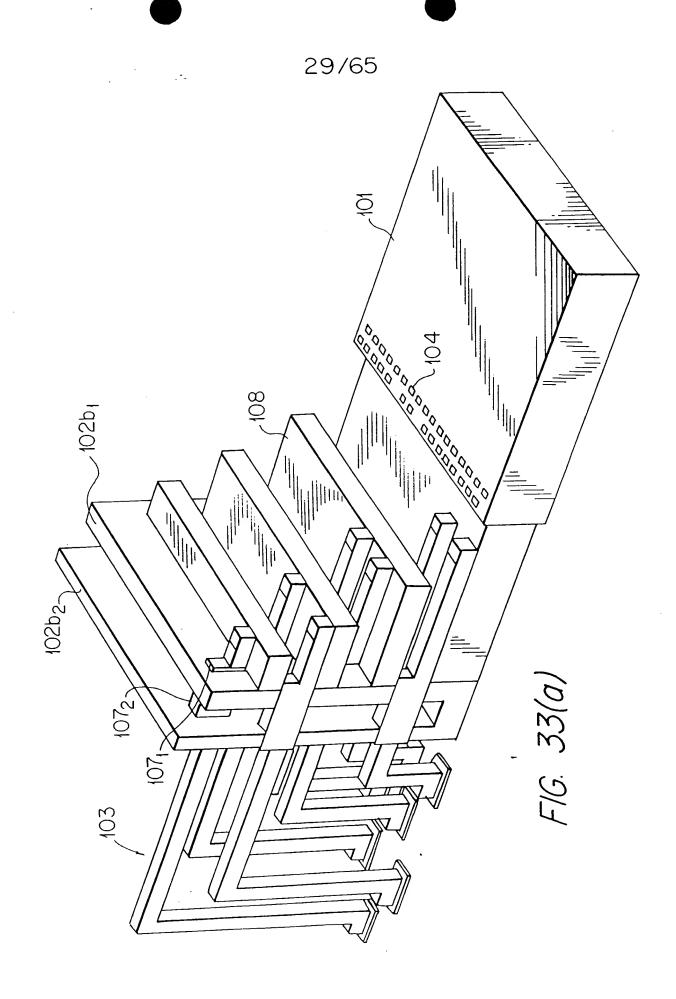


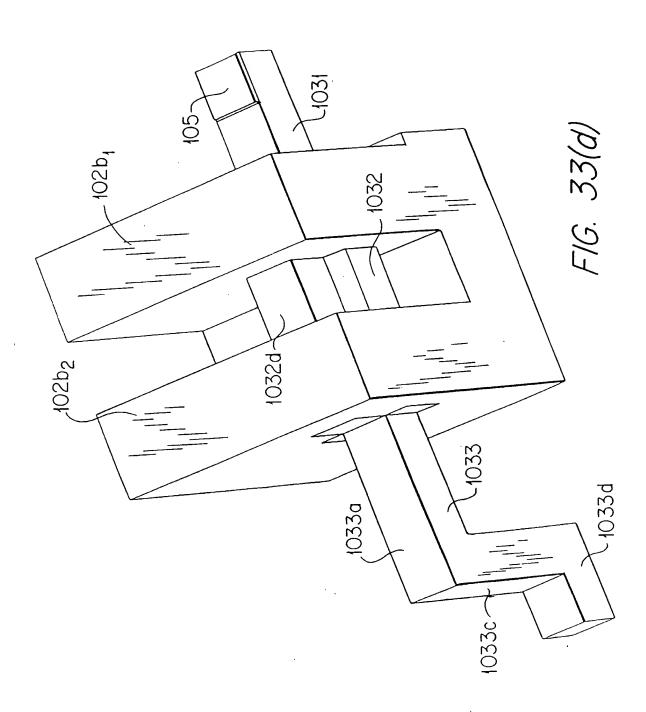


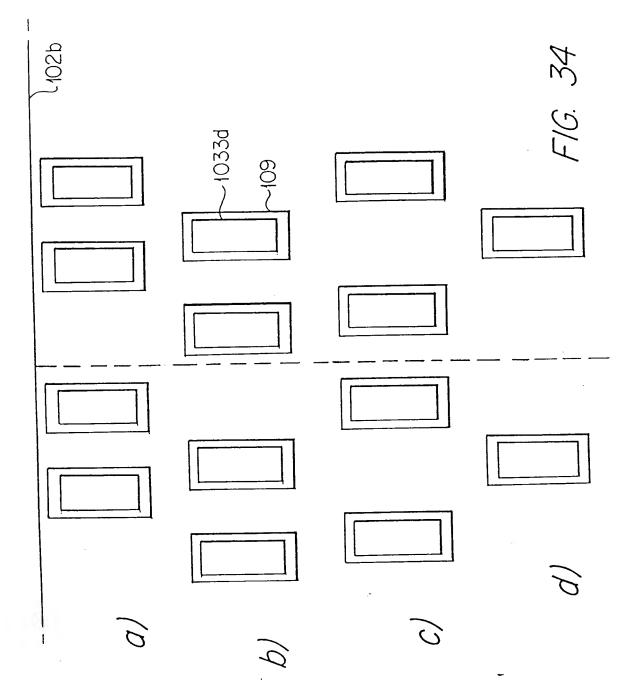


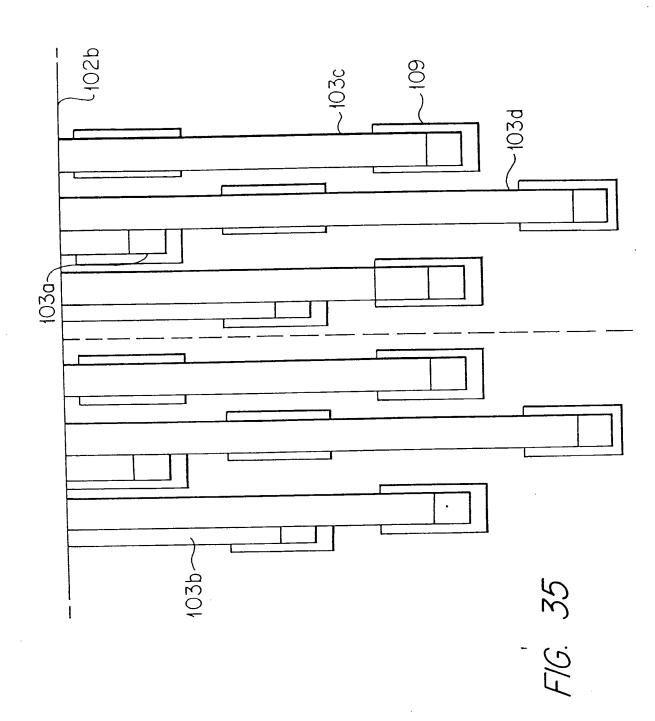
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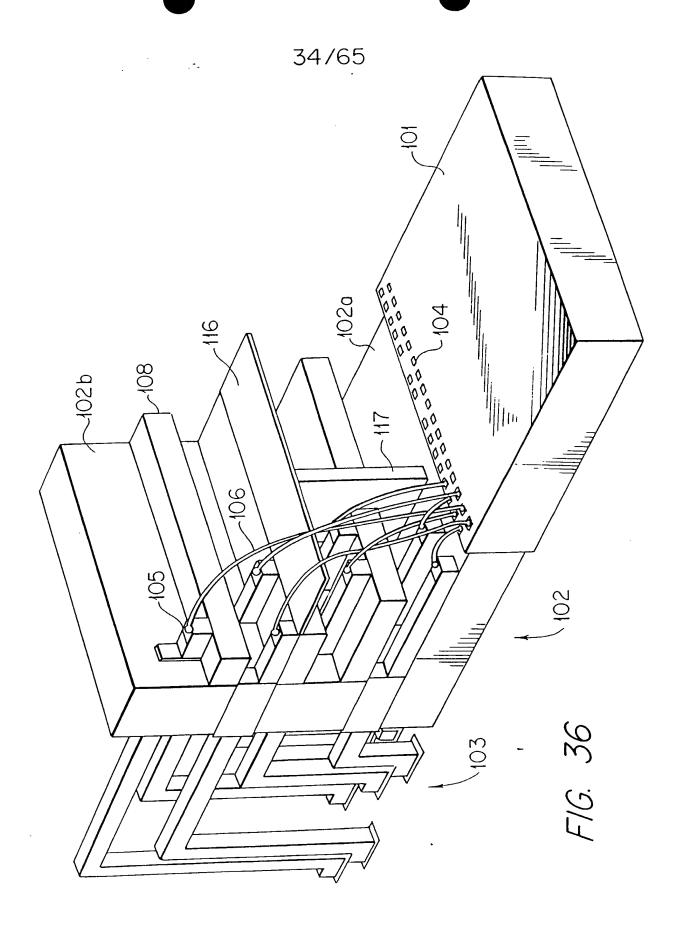


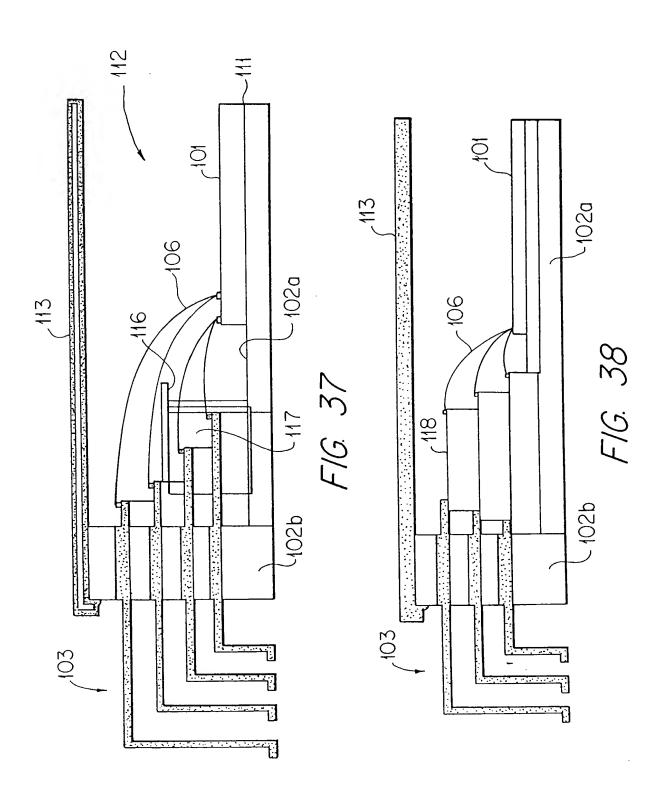


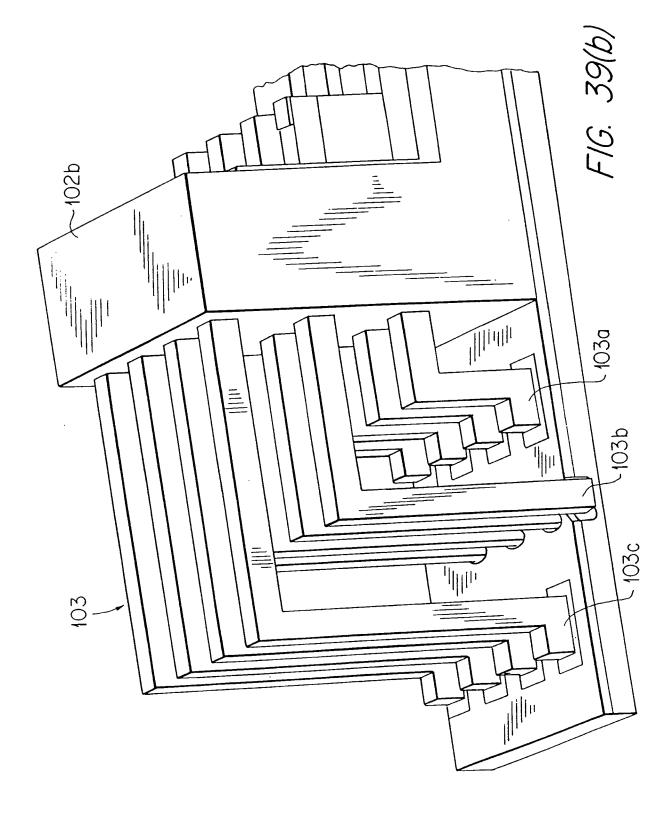


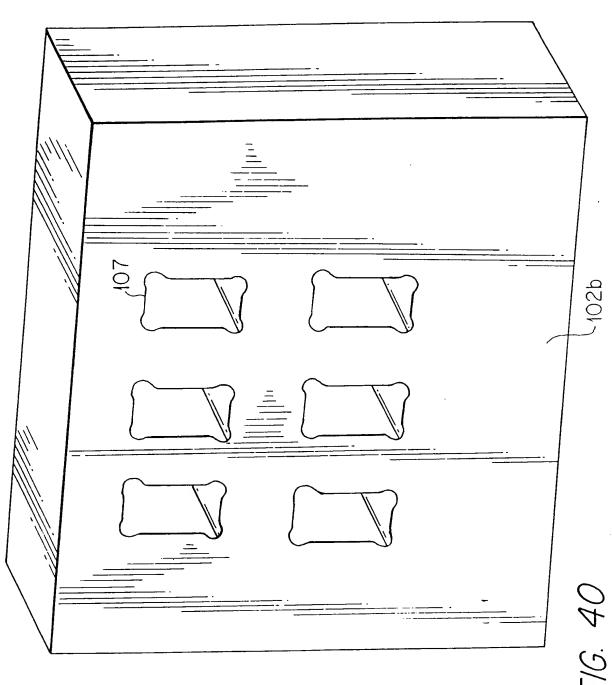


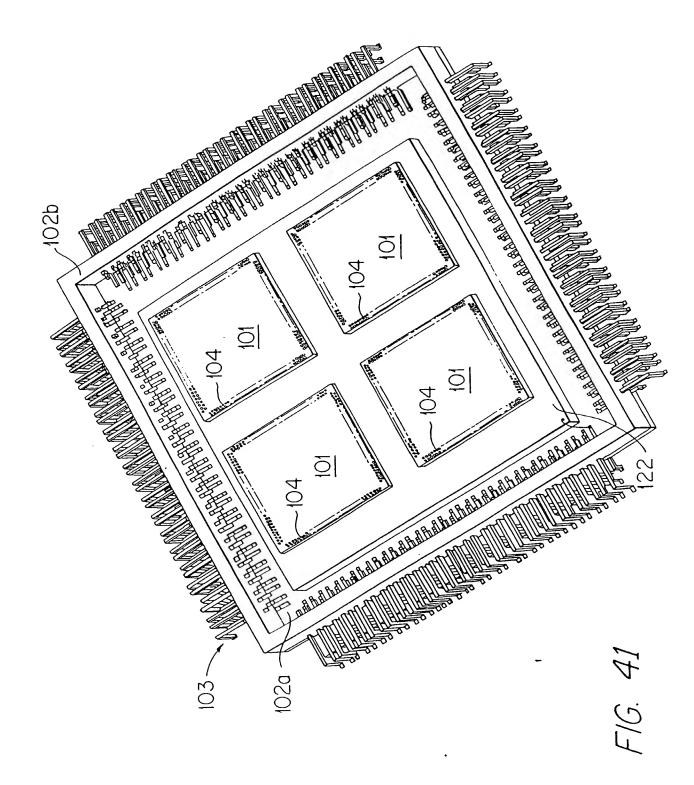


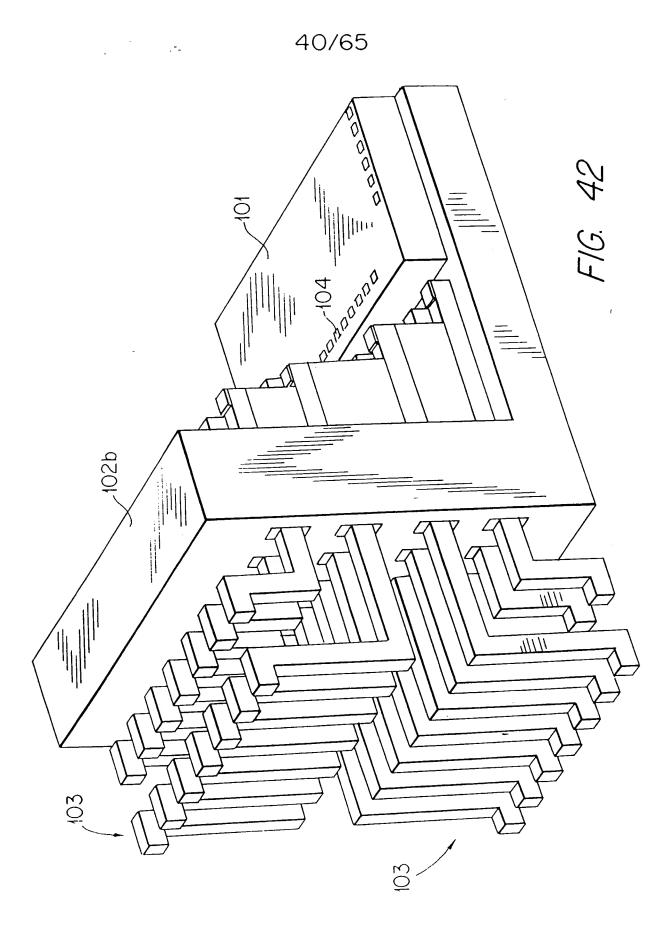


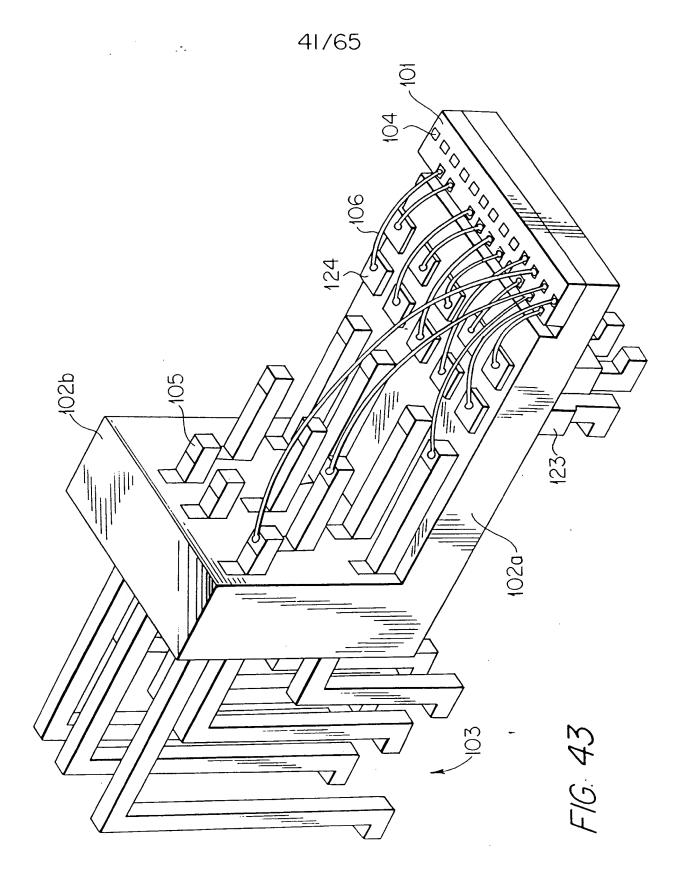












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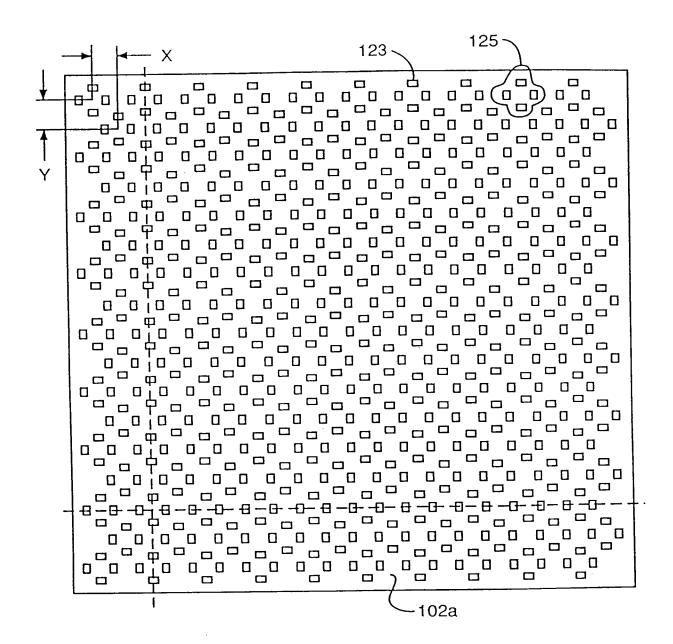
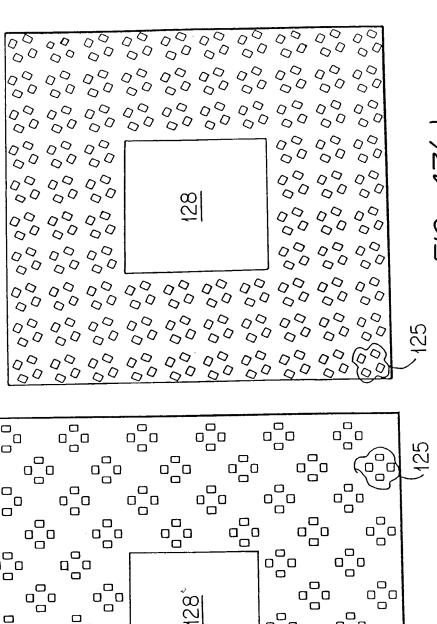


FIG. 44

FIG. 45



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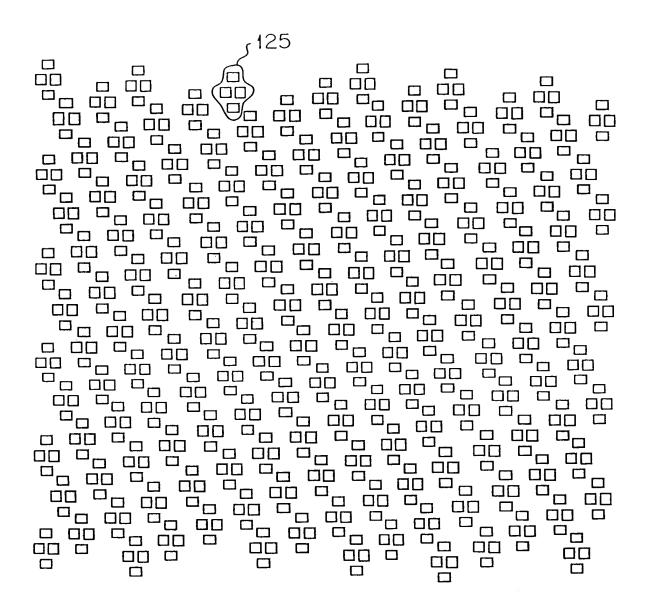
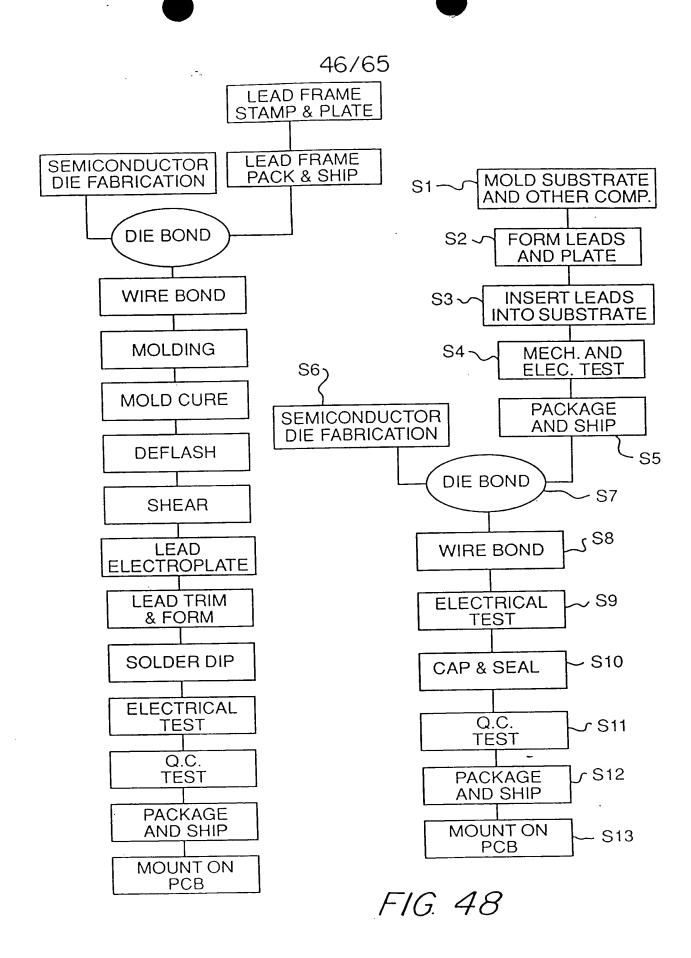
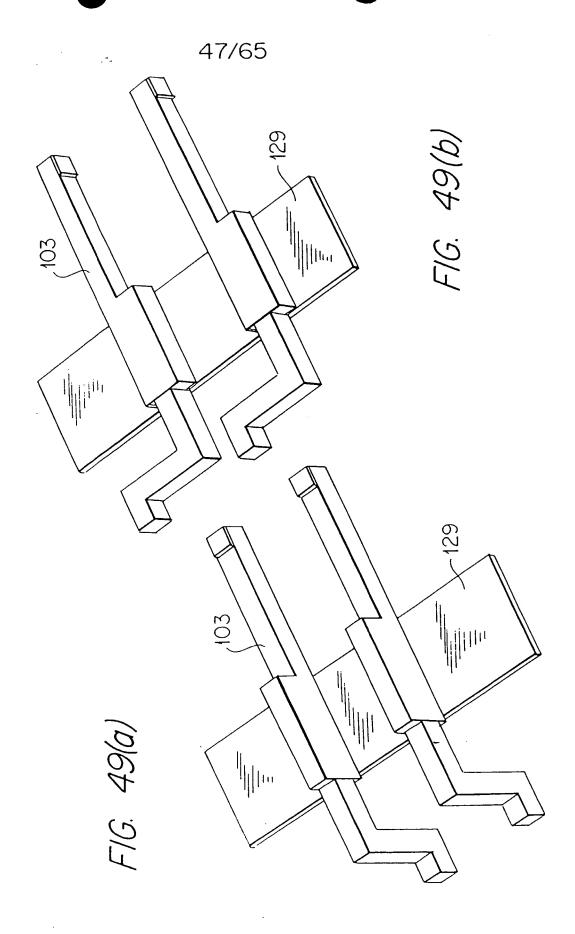
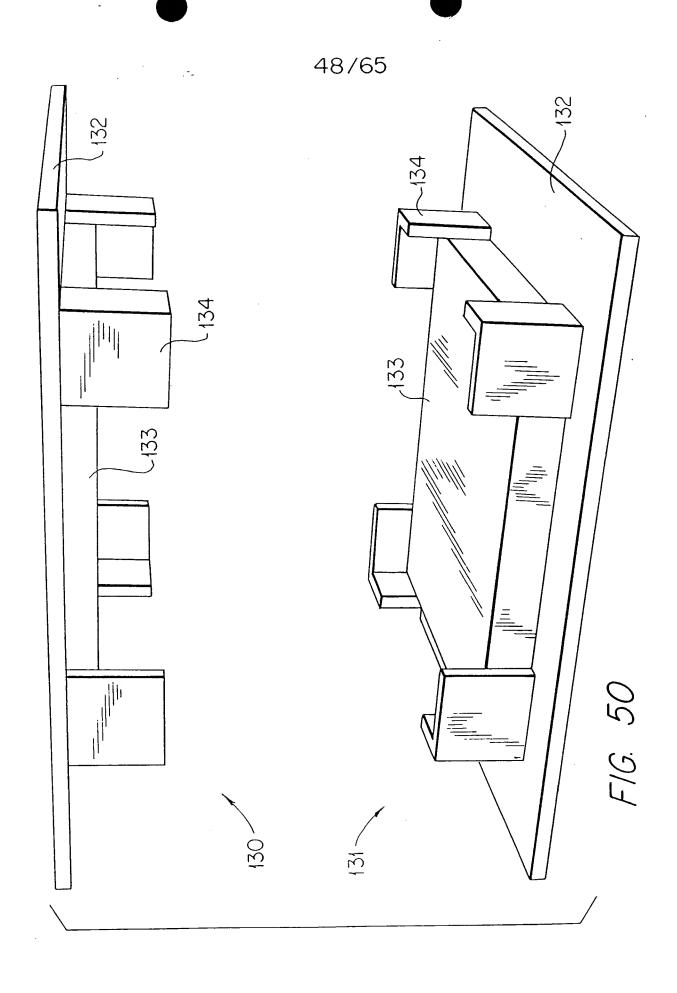


FIG. 47(b)







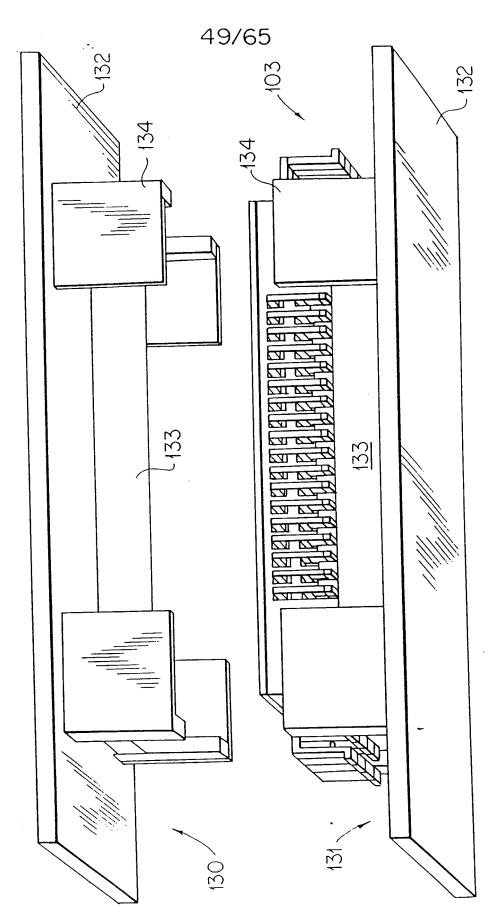
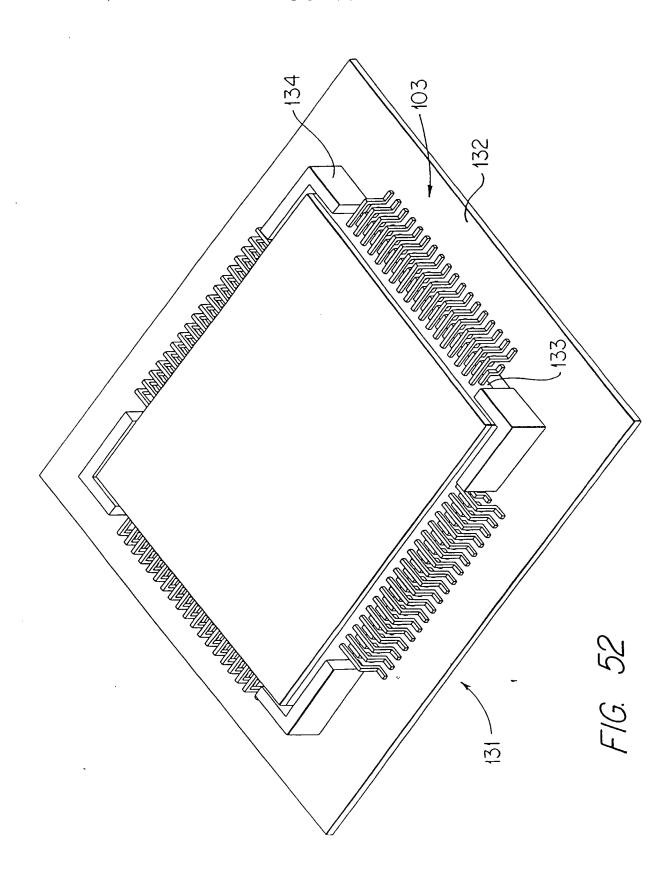
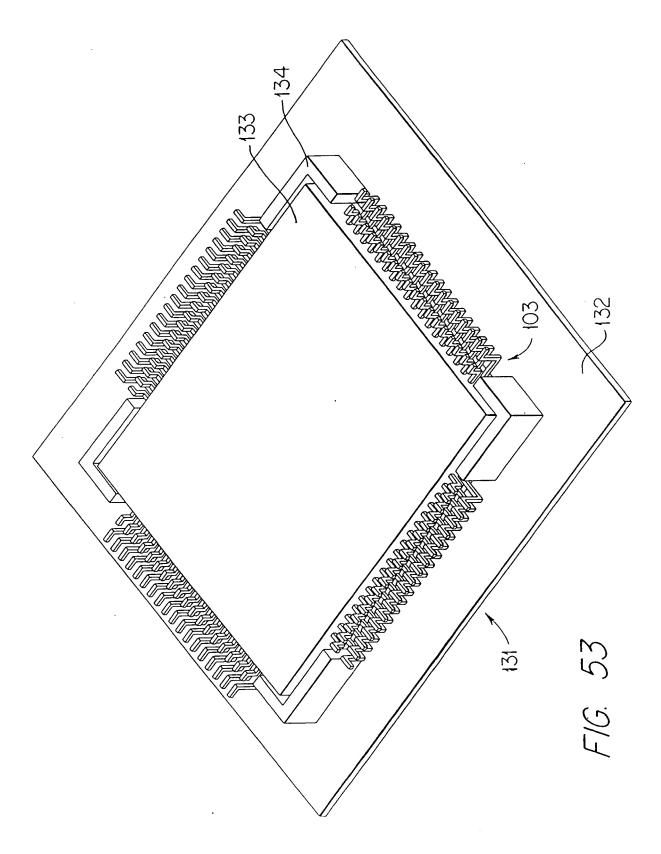
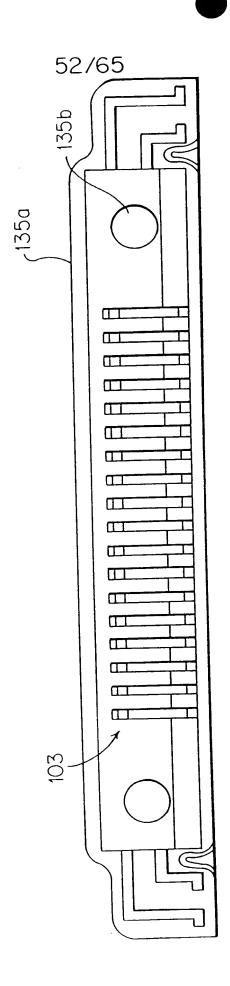


FIG 51

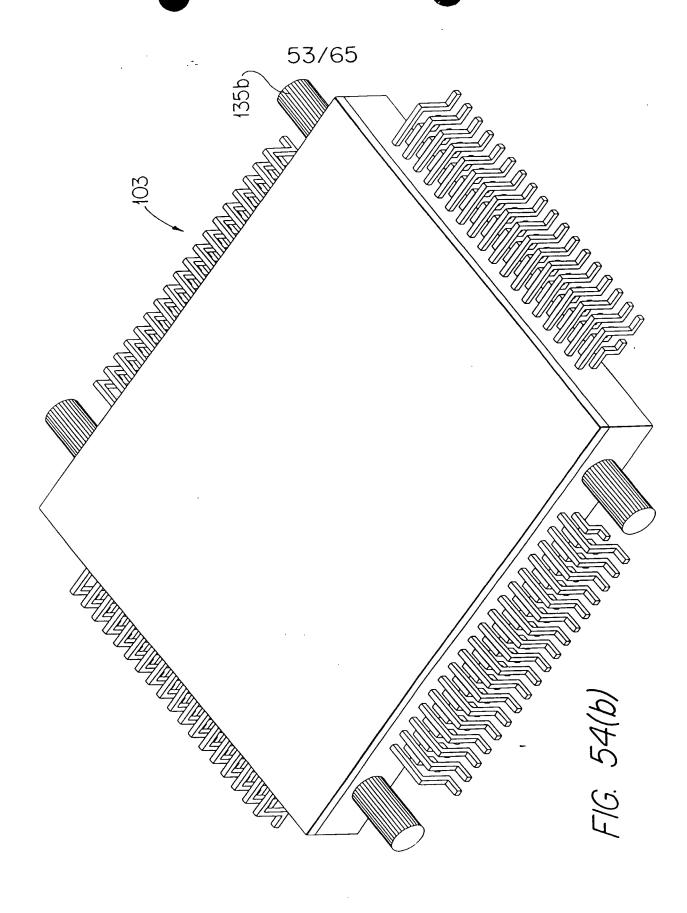
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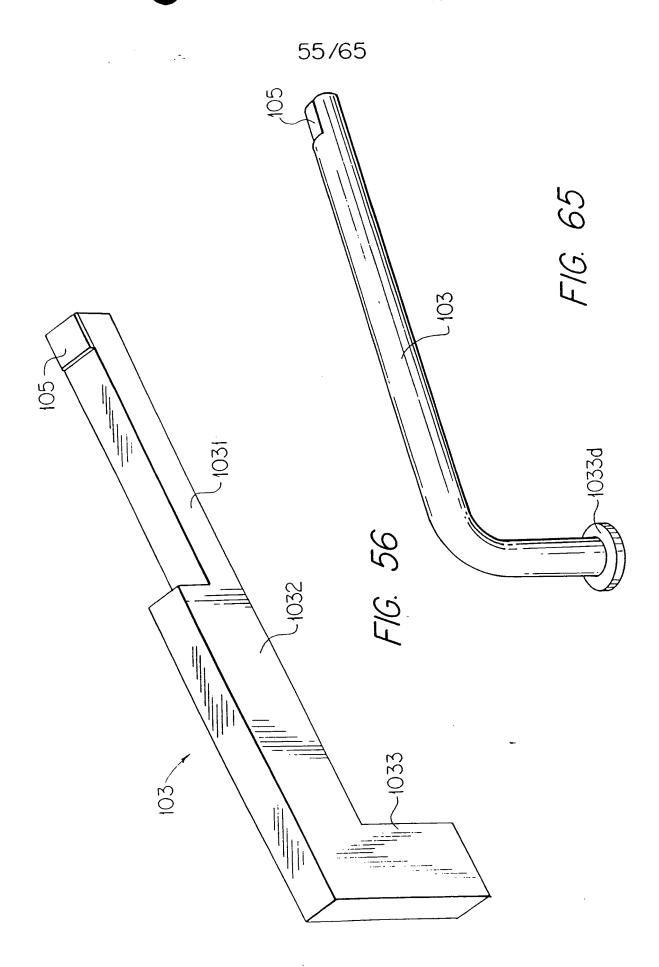






F1G. 54(a)





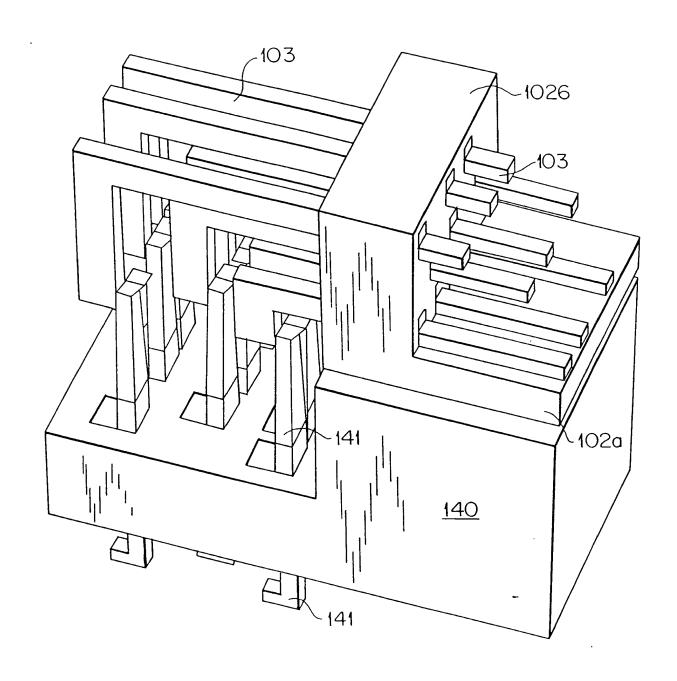
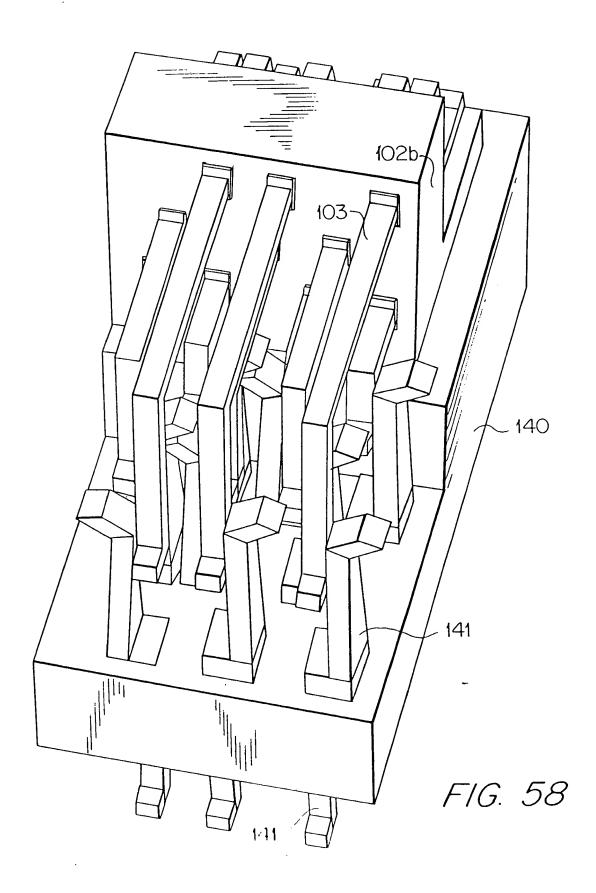


FIG. 57

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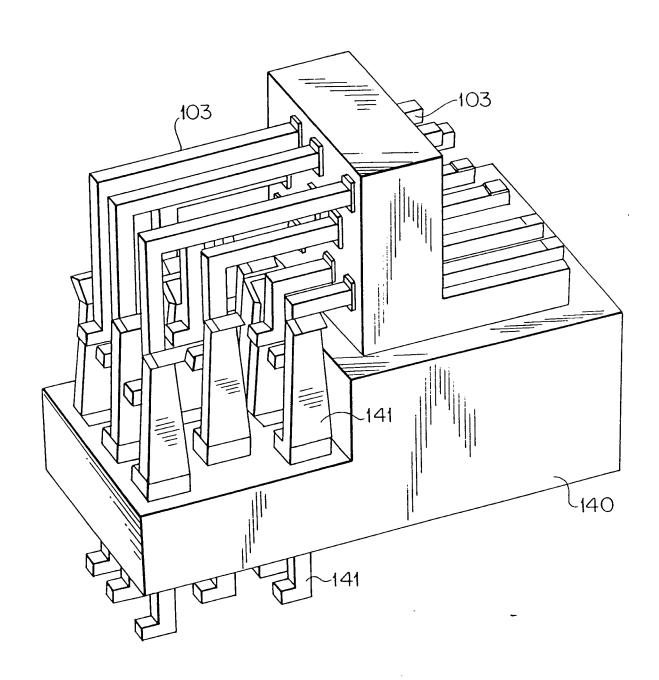
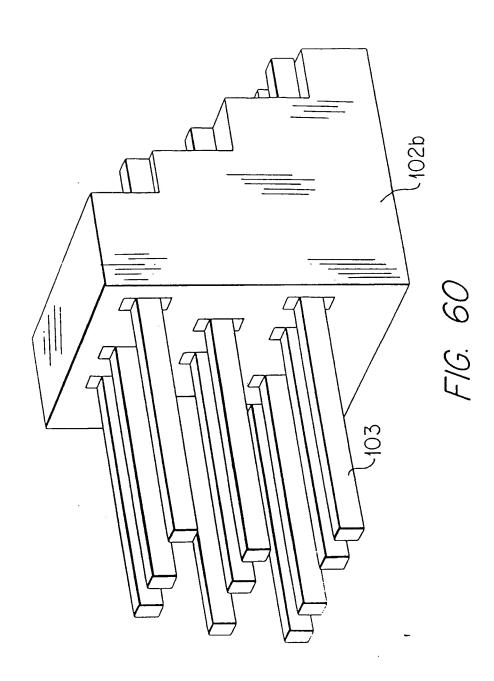
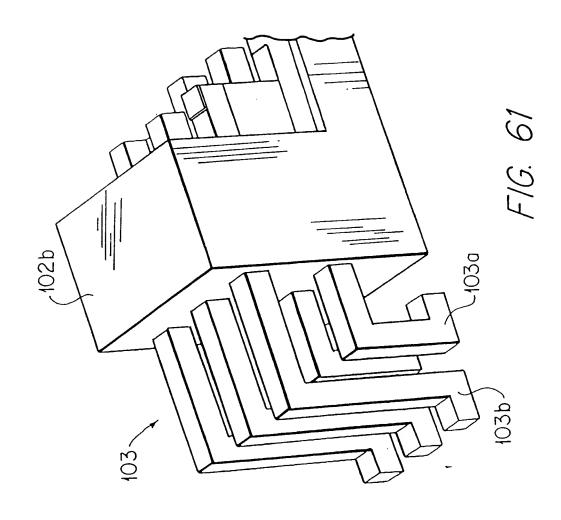
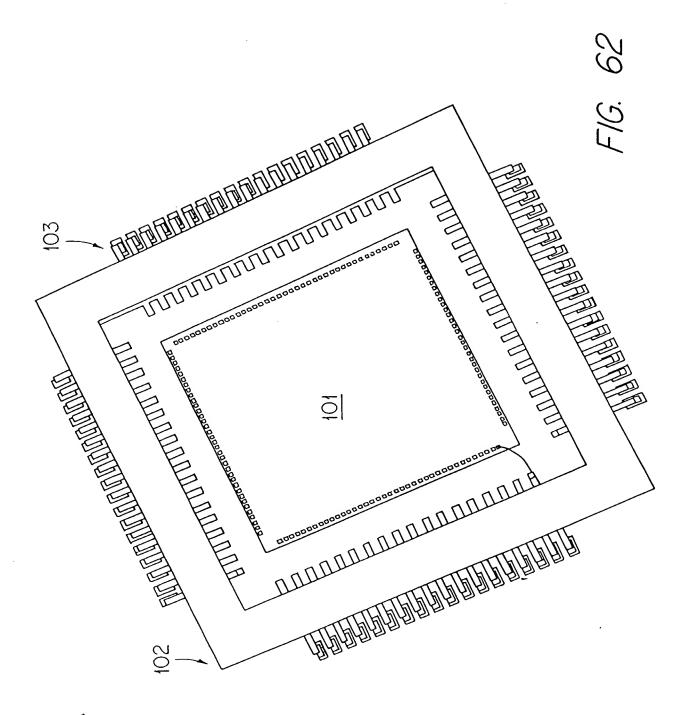


FIG. 59







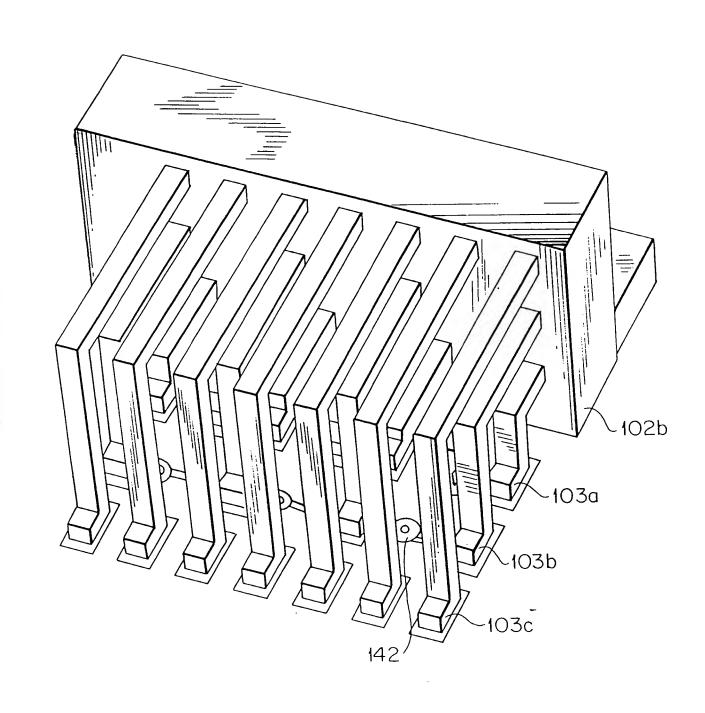


FIG 63

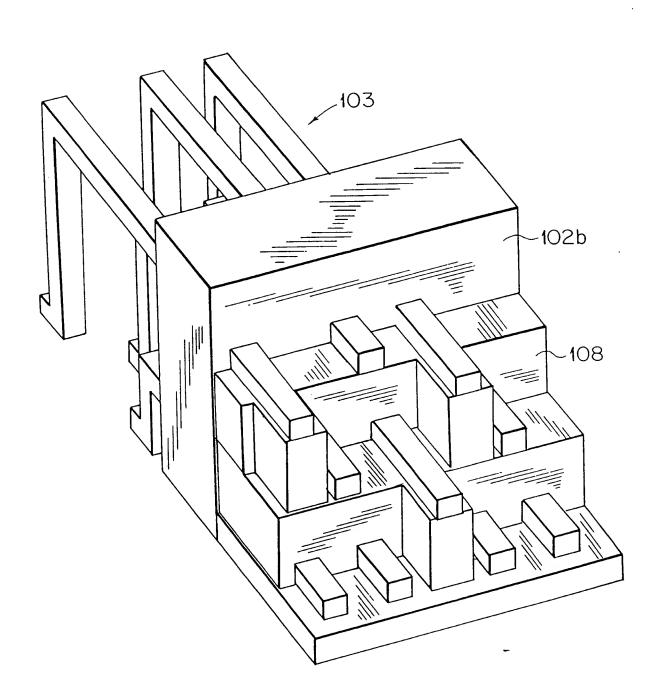


FIG. 64

